DE3S062D

Silicon epitaxial planar type

For surge absorption circuits

■ Features

- High electrostatic discharge ESD
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Total power dissipation *1	P_{T}	150	mW	
Electrostatic discharge *2	ESD	±30	kV	
Junction temperature	T_j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *1: $P_T = 150$ mW achieved with a printed circuit board.

■ Package

• Code

SSMini3-F3-B

- Pin Name
 - 1: Cathode-1
 - 2: Cathode-2
 - 3: Anode-1, 2

■ Marking Symbol: 41

■ Internal Connection



■ Common Electrical Characteristics $T_a = 25$ °C±3°C

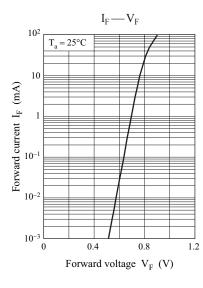
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1,2	V_Z	$I_Z = 1 \text{ mA}$	5.89		6.51	V
Reverse current	I_R	$V_R = 4 V$			1	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		55		pF
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 1 \text{ mA}$		2.3		mV/°C

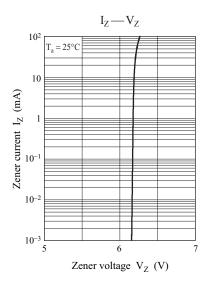
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

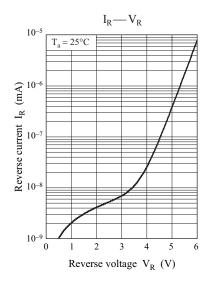
- 2. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
 - $*2: V_Z$ guaranteed 20 ms after current flow.
 - *3: $T_i = 25^{\circ}C$ to $150^{\circ}C$

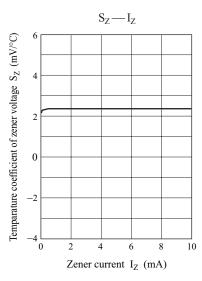
^{*2:} Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

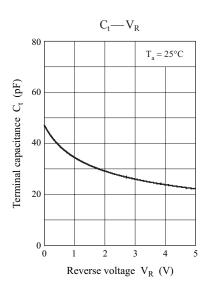
DE3S062D Panasonic







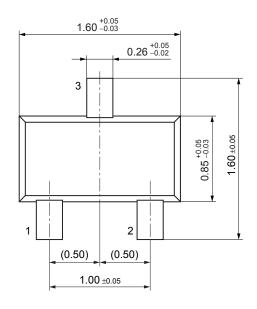


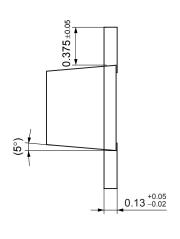


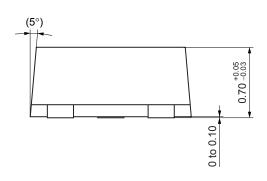
2 Ver. AED

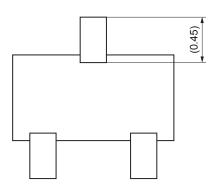
SSMini3-F3-B

Unit: mm









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